

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S9	4	us-20010050444-\$.did. or us-20020150840-\$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:06
S10	24017	(stamp\$4 or emboss\$6 or mold\$4 or mould\$4) with (Ni or nickel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:28
S11	12893	(stamp\$4 or emboss\$6 or mold\$4 or mould\$4) with (ag or silver)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:28
S12	36198	(stamp\$4 or emboss\$6 or mold\$4 or mould\$4) with (Cu or copper)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:29
S13	668584	(Ni or nickel) near10 (au or gold or ru or ruthenium or cu or copper or mg or magnesium or si or silicon or ti or titanium or silver or ag or p or phosphorous) or NIP	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:30
S14	753195	(Ni or nickel) with (au or gold or ru or ruthenium or cu or copper or mg or magnesium or si or silicon or ti or titanium or silver or ag or p or phosphorous) or NIP	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:31
S15	753195	((Ni or nickel) with (au or gold or ru or ruthenium or cu or copper or mg or magnesium or si or silicon or ti or titanium or silver or ag or p or phosphorous)) or NIP	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:31
S16	10615	S10 same S15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:31

S17	202546	((Ni or nickel) with (au or gold or ru or ruthenium or cu or copper or mg or magnesium or si or silicon or ti or titanium or silver or ag or p or phosphorous)) or NIP) with (film or coating or layer or surface)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:32
S18	3527	S10 same S17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:32
S19	87288	((ag or silver) with (au or gold or cu or copper)) with (film or coating or layer or surface)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:33
S20	90542	((Cu or copper) with (ag or silver or ti or titanium)) with (film or coating or layer or surface)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:33
S21	1418	S11 same S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:34
S22	1203	S12 same S20	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:34
S23	30070	(S17 or S19 or S20) and (electroplat\$6 or electroform\$6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:36
S24	13996	(S17 or S19 or S20) same (electroplat\$6 or electroform\$6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:36
S25	928	S24 same (passivat\$6 or releas\$6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:37
S26	21	S22 and S25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:38

S27	835435	((optical or laser or information) near5 (media or medium or disc or disk)) or hologra\$6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/13 10:42
S28	22245	(stamp\$4 or emboss\$6 or mold\$4 or mould\$4) with S27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:43
S29	52	S22 and S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:43
S30	147	S21 and S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:43
S31	429	S16 and S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:43
S32	39	S29 and @ad< "20040407"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:44
S33	80	S30 and @ad< "20040407"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:44
S34	288	S31 and @ad< "20040407"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 10:44
S35	89463	(((((Ni or nickel) near8 alloy \$4) with (au or gold or ru or ruthenium or cu or copper or mg or magnesium or si or silicon or ti or titanium or silver or ag or p or phosphorous)) or NIP) with (film or coating or layer or surface)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 11:38

S36	19944	((Cu or copper) near5 alloy\$4) with (ag or silver or ti or titanium)) with (film or coating or layer or surface)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 11:38
S37	1934	S10 and S35	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 11:39
S38	653	S12 and S36	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 11:39
S39	248	S12 same S36	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 11:39
S40	192	S39 and @ad<"20040407"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 11:39
S41	1106	S10 and (nip or "ni-p" or ((ni or nickel) adj2 (p or phosphorous)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 11:50
S42	1806237	(stamp\$4 or emboss\$6 or mold\$4 or mould\$4 or S27).ti,ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 11:50
S43	552	S41 and S42	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 11:51
S44	395	S43 and @ad<"20040407"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 11:51
S45	67	(S27).ti,ab. and S44	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 11:51

S46	67906	((Cu or copper) near5 (alloy\$3 or additive or added)) with (ag or silver or ti or titanium)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/13 12:13
S47	497	S28 and S46	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:14
S48	18277	S28 and S42	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:14
S49	4298	S46 and S42	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:14
S50	1670	(S27).ti,ab. and S49	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:15
S51	1415782	(stamp\$4 or emboss\$6 or mold\$4 or mould\$4).ti,ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:15
S52	77	(S27).ti,ab. and S51 and S49	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:15
S53	2678	(stamp\$4 or emboss\$6 or mold\$4 or mould\$4) same S46	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:16
S54	28	(S27).ti,ab. and S51 and S53	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:17
S55	1762	(passivat\$6 or separat\$4 or peel\$6 or remov\$4) and S53	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:19
S56	98	(passivat\$6 or separat\$4 or peel\$6 or remov\$4) and S53	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:19

S57	17291	(stamp\$4 or emboss\$6 or mold\$4 or mould\$4) near5 (Cu or copper)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:29
S58	413	S46 same S57	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/13 12:29
S59	13	(S27).ti,ab. and S58	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:30
S60	1172	(passivat\$6 or separat\$4 or peel\$6 or remov\$4 or oxidiz\$6 or permanganate) same S46	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:31
S61	96	(S51 or S27.ti,ab.) and S60	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:32
S62	904246	((optical or laser or information or video) near5 (media or medium or disc or disk)) or hologra \$6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/13 12:36
S63	129057	(Cu or copper) adj2 alloy	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/13 12:37
S64	4625	(Cu or copper) adj2 alloy same (electroform\$6 or electroplat\$6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/13 12:37
S65	284	(stamp\$4 or emboss\$6 or mold\$4 or mould\$4) same S64	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:37
S66	19	S65 and S62	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/13 12:38

S67	5308	(Cu or copper) near2 alloy same (electroform\$6 or electroplat\$6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/13 12:41
S68	341	(stamp\$4 or emboss\$6 or mold\$4 or mould\$4) same S67	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:41
S69	21	S68 and S62	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/13 12:42
S70	2	S69 not S66	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/13 12:42
S71	1438	(ag or silver) near2 alloy same (electroform\$6 or electroplat\$6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/13 12:43
S72	51	(stamp\$4 or emboss\$6 or mold\$4 or mould\$4) same S71	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:43
S73	4	S72 and S62	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/13 12:43
S74	2	JP-11000922-\$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/13 12:44
S75	32	S72 and @ad< "20040407"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:45
S76	62412	((Cu or copper) near5 (alloy\$4)) with (film or coating or layer or surface)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:49

S77	27610	((ag or silver) near5 (alloy \$4)) with (film or coating or layer or surface)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:50
S78	38111	(stamp\$4 or emboss\$6 or mold\$4 or mould\$4 or electroplat\$6 or electro or electroform or plat\$4) same (S19 or S77)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:51
S79	443731	((optical or laser or information or video) near5 (media or medium or disc or disk)) or hologra \$6).ti,ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/13 12:52
S80	1197	S78 and S79	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/13 12:52
S81	0	((optical or laser or information or video) near5 (media or medium or disc or disk)).ti,ab. and I80and	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/13 12:52
S82	1089	((optical or laser or information or video) near5 (media or medium or disc or disk)).ti,ab. and S80	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/13 12:53
S83	30073	(stamp\$4 or emboss\$6 or mold\$4 or mould\$4) same S27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:53
S84	46900	(stamp\$4 or emboss\$6 or mold\$4 or mould\$4 or electroplat\$6 or electro or electroform or plat\$4) same (S20 or S76)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:54
S85	469	S83 and S84	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:55
S86	25170	S78 and S84	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:55



S87	816	S78 and S83	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:56
S88	269	S85 and @ad<"20040407"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:56
S89	424	S87 and @ad<"20040407"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/02/13 12:56
S90	159	((optical or laser or information or video) near5 (media or medium or disc or disk)).ti,ab. and S88	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/13 12:57
S91	234	((optical or laser or information or video) near5 (media or medium or disc or disk)).ti,ab. and S89	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/13 12:57
S92	97	S91 not S90	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/13 13:04

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